

ULTRA FAST RECOVERY POWER RECTIFIER

Absolute Maximum Ratings (per diode) T_C=25°C unless otherwise noted

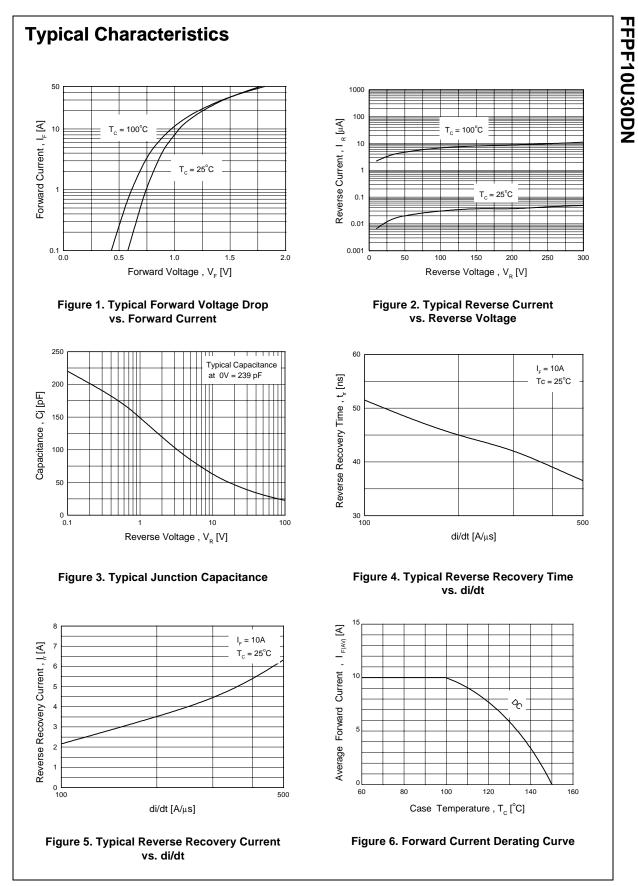
Symbol	Parameter	Value	Units
V _{RRM}	Peak Repetitive Reverse Voltage	300	V
I _{F(AV)}	Average Rectified Forward Current@ $T_C = 100^{\circ}C$	10	A
I _{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	100	A
T _{J,} T _{STG}	Operating Junction and Storage Temperature	- 65 to +150	°C

Thermal Characteristics

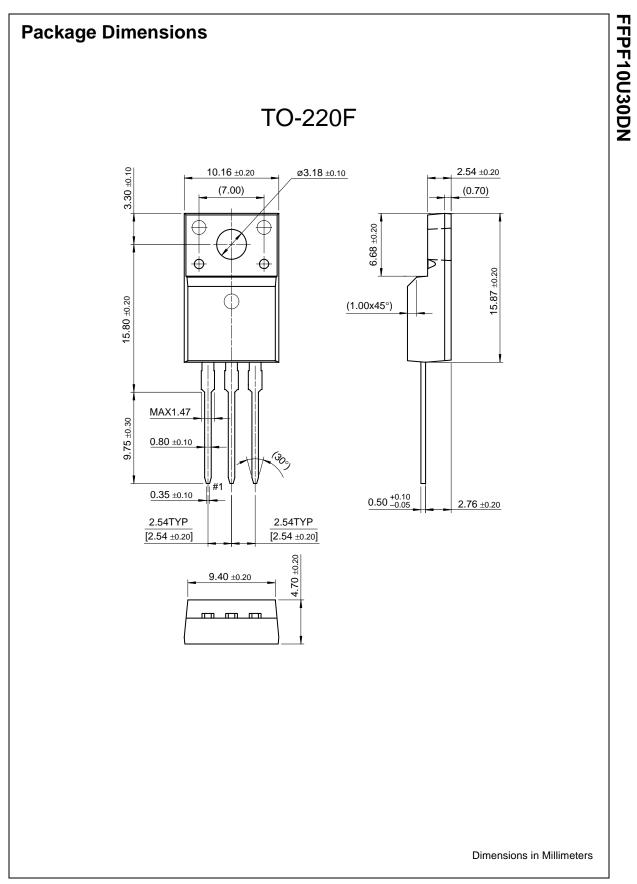
Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	2.1	°C/W

Electrical Characteristics (per diode) T_C=25 °C unless otherwise noted

Symbol	Parameter		Min.	Тур.	Max.	Units
V _{FM} *	Maximum Instantaneous Forward Voltage					V
	I _F = 10A	T _C = 25 °C	-	-	1.2	
	I _F = 10A	T _C = 25 °C T _C = 100 °C	-	-	1.1	
RM *	Maximum Instantaneous Reverse Current					μΑ
	@ rated V _R	T _C = 25 °C	-	-	10	
		T _C = 25 °C T _C = 100 °C	-	-	100	
trr	Maximum Reverse Recovery Time		-	-	60	ns
rr	Maximum Reverse Recovery Current		-	-	4.5	А
Q _{rr}	Maximum Reverse Recovery Charge (I _F =10A, di/dt = 200A/μs)		-	-	135	nC
W _{AVL}	Avalanche Energy		1.0	-	-	mJ



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EcoSPARK™ E ² CMOS™	ISOPLANAR™ LittleFET™	QT Optoelectronics™ Quiet Series™	UltraFET [®] VCX™
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